

RELIABILITY REPORT
FOR
MAX4622xxE
PLASTIC ENCAPSULATED DEVICES

January 30, 2003

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by



Jim Pedicord
Quality Assurance
Reliability Lab Manager

Reviewed by



Bryan J. Preeshl
Quality Assurance
Executive Director

Conclusion

The MAX4622 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX4622 is a precision, dual, high-speed analog switch. The single-pole/double-throw (SPDT) MAX4622 has two normally closed (NC) and two NO poles. The part offers low 5 ohms on-resistance guaranteed to match to within 0.5 ohm between channels and to remain flat over the full analog signal range ($\Delta 0.5$ ohm max). It also offers low leakage (<500pA at +25°C, <5nA at +85°C) and fast switching times (turn-on time <250ns, turn-off time <200ns).

This analog switch is ideal in low-distortion applications and is the preferred solution over mechanical relays in automatic test equipment or applications where current switching is required. It has low power requirements, use less board space, and are more reliable than mechanical relays.

The MAX4622 is a pin-compatible replacement for the DG403 offering improved overall performance. This monolithic switch operates from a single positive supply (+4.5V to +36V) or with bipolar supplies ($\pm 4.5V$ to $\pm 18V$) while retaining CMOS-logic input compatibility.

B. Absolute Maximum Ratings

| <u>Item</u> | <u>Rating</u> |
|--|----------------------------|
| (Voltages Referenced to GND) | |
| V+ to GND | -0.3V to +44V |
| V- to GND | +0.3V to -44V |
| V+ to V- | -0.3V to +44V |
| VL to GND | -0.3V to (V+ + 0.3V) |
| All Other Pins to GND (Note 1) | (V- - 0.3V) to (V+ + 0.3V) |
| Continuous Current (COM_, NO_, NC_) | $\pm 100mA$ |
| Peak Current (COM_, NO_, NC_) (pulsed at 1ms, 10% duty cycle) | $\pm 300mA$ |
| Operating Temperature Ranges | |
| MAX4622C_ _ | 0°C to +70°C |
| MAX4622E_ _ | -40°C to +85°C |
| Storage Temperature Range | -65°C to +150°C |
| Lead Temperature (soldering, 10sec) | +300°C |
| Continuous Power Dissipation (TA = +70°C) | |
| 16-Pin NSO | 696mW |
| 16-Pin PDIP | 842mW |
| Derates above +70°C | |
| 16-Pin NSO | 8.70mW/°C |
| 16-Pin PDIP | 10.53mW/°C |
| Note 1: Signals on NC_, NO_, COM_, or IN_ exceeding V+ or V- will be clamped by internal diodes. Limit forward diode current to maximum | |

II. Manufacturing Information

| | |
|----------------------------------|--|
| A. Description/Function: | Dual, 5 Ohm Analog Switches |
| B. Process: | S5HV - Medium voltage 5 micron silicon gate CMOS |
| C. Number of Device Transistors: | 82 |
| D. Fabrication Location: | Oregon, USA |
| E. Assembly Location: | Philippines or Malaysia |
| F. Date of Initial Production: | July, 1999 |

III. Packaging Information

| | | |
|--|--------------------------|--------------------------|
| A. Package Type: | 16-Lead NSO | 16-Lead PDIP |
| B. Lead Frame: | Copper | Copper |
| C. Lead Finish: | Solder Plate | Solder Plate |
| D. Die Attach: | Silver-filled Epoxy | Silver-filled Epoxy |
| E. Bondwire: | Gold (1.3 mil dia.) | Gold (1.3 mil dia.) |
| F. Mold Material: | Epoxy with silica filler | Epoxy with silica filler |
| G. Assembly Diagram: | # 05-1201-0084 | # 05-1201-0083 |
| H. Flammability Rating: | Class UL94-V0 | Class UL94-V0 |
| I. Classification of Moisture Sensitivity per JEDEC standard JESD-020-A: | Level 1 | Level 1 |

IV. Die Information

| | |
|----------------------------|---|
| A. Dimensions: | 86 x 188 mils |
| B. Passivation: | Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide) |
| C. Interconnect: | Aluminum/Si (Si = 1%) |
| D. Backside Metallization: | None |
| E. Minimum Metal Width: | 5 microns (as drawn) |
| F. Minimum Metal Spacing: | 5 microns (as drawn) |
| G. Bondpad Dimensions: | 5 mil. Sq. |
| H. Isolation Dielectric: | SiO ₂ |
| I. Die Separation Method: | Wafer Saw |

V. Quality Assurance Information

- A. Quality Assurance Contacts: Jim Pedicord (Manager, Rel Operations)
Bryan Preeshl (Executive Director of QA)
Kenneth Huening (Vice President)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4389 \times 80 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

└ Temperature Acceleration factor assuming an activation energy of 0.8eV

$$\lambda = 13.57 \times 10^{-9} \quad \lambda = 13.57 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

This low failure rate represents data collected from Maxim's reliability qualification and monitor programs. Maxim also performs weekly Burn-In on samples from production to assure reliability of its processes. The reliability required for lots which receive a burn-in qualification is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on rejects from lots exceeding this level. The attached Burn-In Schematic (Spec. # 06-1727) shows the static circuit used for this test. Maxim also performs 1000 hour life test monitors quarterly for each process. This data is published in the Product Reliability Report (**RR-1M**).

B. Moisture Resistance Tests

Maxim evaluates pressure pot stress from every assembly process during qualification of each new design. Pressure Pot testing must pass a 20% LTPD for acceptance. Additionally, industry standard 85°C/85%RH or HAST tests are performed quarterly per device/package family.

C. E.S.D. and Latch-Up Testing

The AH22 die type has been found to have all pins able to withstand a transient pulse of $\pm 2000\text{V}$, per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of $\pm 250\text{mA}$.

Table 1
Reliability Evaluation Test Results

MAX4622xxE

| TEST ITEM | TEST CONDITION | FAILURE IDENTIFICATION | PACKAGE | SAMPLE SIZE | NUMBER OF FAILURES |
|-----------------------------------|---|----------------------------------|---------|-------------|--------------------|
| Static Life Test (Note 1) | | | | | |
| | Ta = 135°C Biased Time = 192 hrs. | DC Parameters & functionality | | 80 | 0 |
| Moisture Testing (Note 2) | | | | | |
| Pressure Pot | Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs. | DC Parameters & functionality | PDIP | 77 | 0 |
| | | | NSO | 77 | 0 |
| 85/85 | Ta = 85°C RH = 85% Biased Time = 1000hrs. | DC Parameters & functionality | | 77 | 0 |
| Mechanical Stress (Note 2) | | | | | |
| Temperature Cycle | -65°C/150°C 1000 Cycles Method 1010 | DC Parameters & functionality | | 77 | 0 |

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

| | Terminal A (Each pin individually connected to terminal A with the other floating) | Terminal B (The common combination of all like-named pins connected to terminal B) |
|----|---|---|
| 1. | All pins except V_{PS1} <u>3/</u> | All V_{PS1} pins |
| 2. | All input and output pins | All other input-output pins |

1/ Table II is restated in narrative form in 3.4 below.

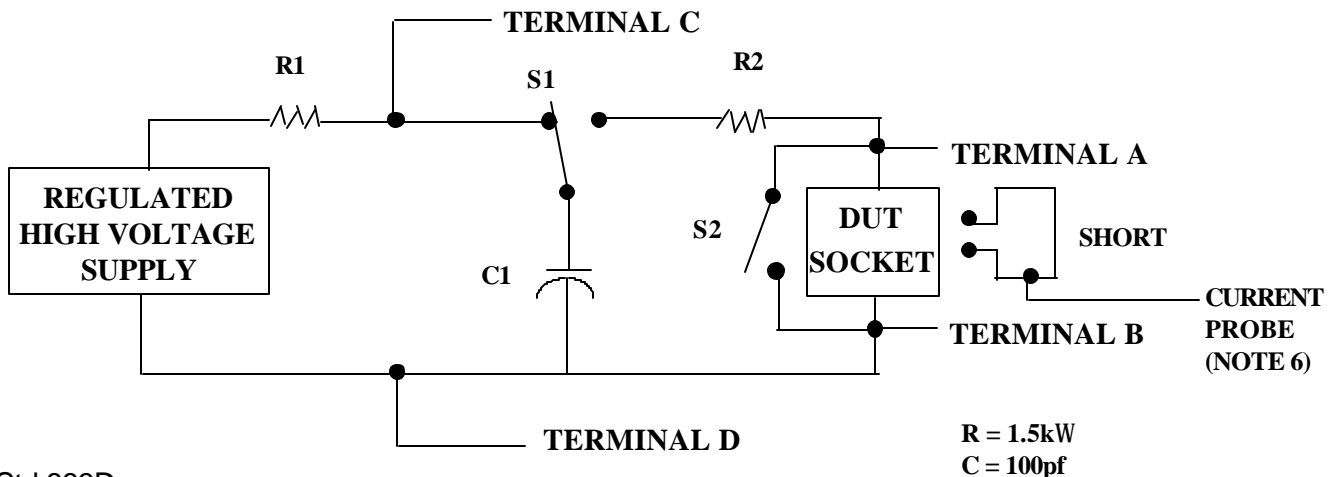
2/ No connects are not to be tested.

3/ Repeat pin combination I for each named Power supply and for ground

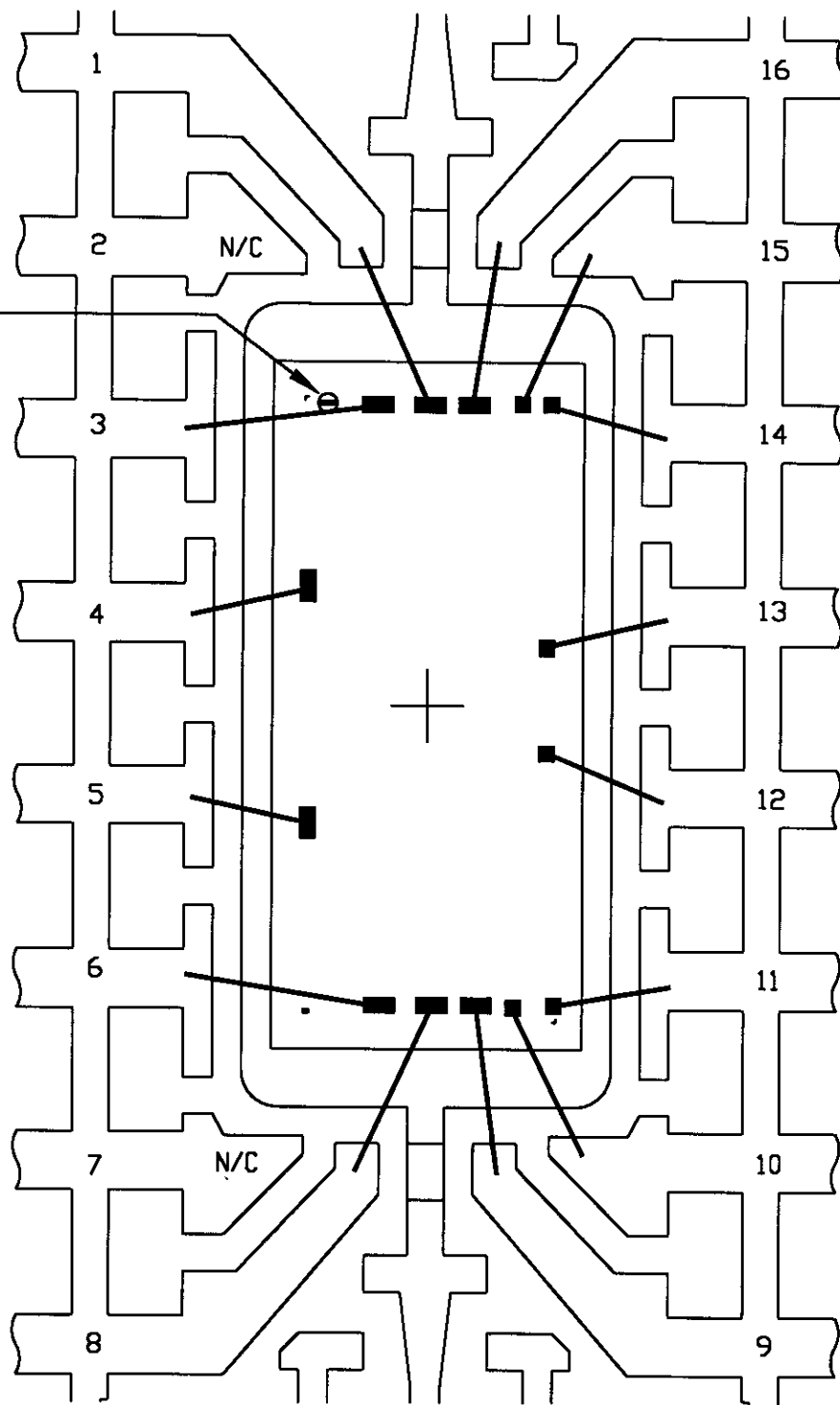
(e.g., where V_{PS1} is V_{DD} , V_{CC} , V_{SS} , V_{BB} , GND, $+V_S$, $-V_S$, V_{REF} , etc).

3.4 Pin combinations to be tested.

- a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.
- b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1} , or V_{SS2} or V_{SS3} or V_{CC1} , or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.
- c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.



DIE
I.D.



PKG.CODE: S16-8

APPROVALS

DATE

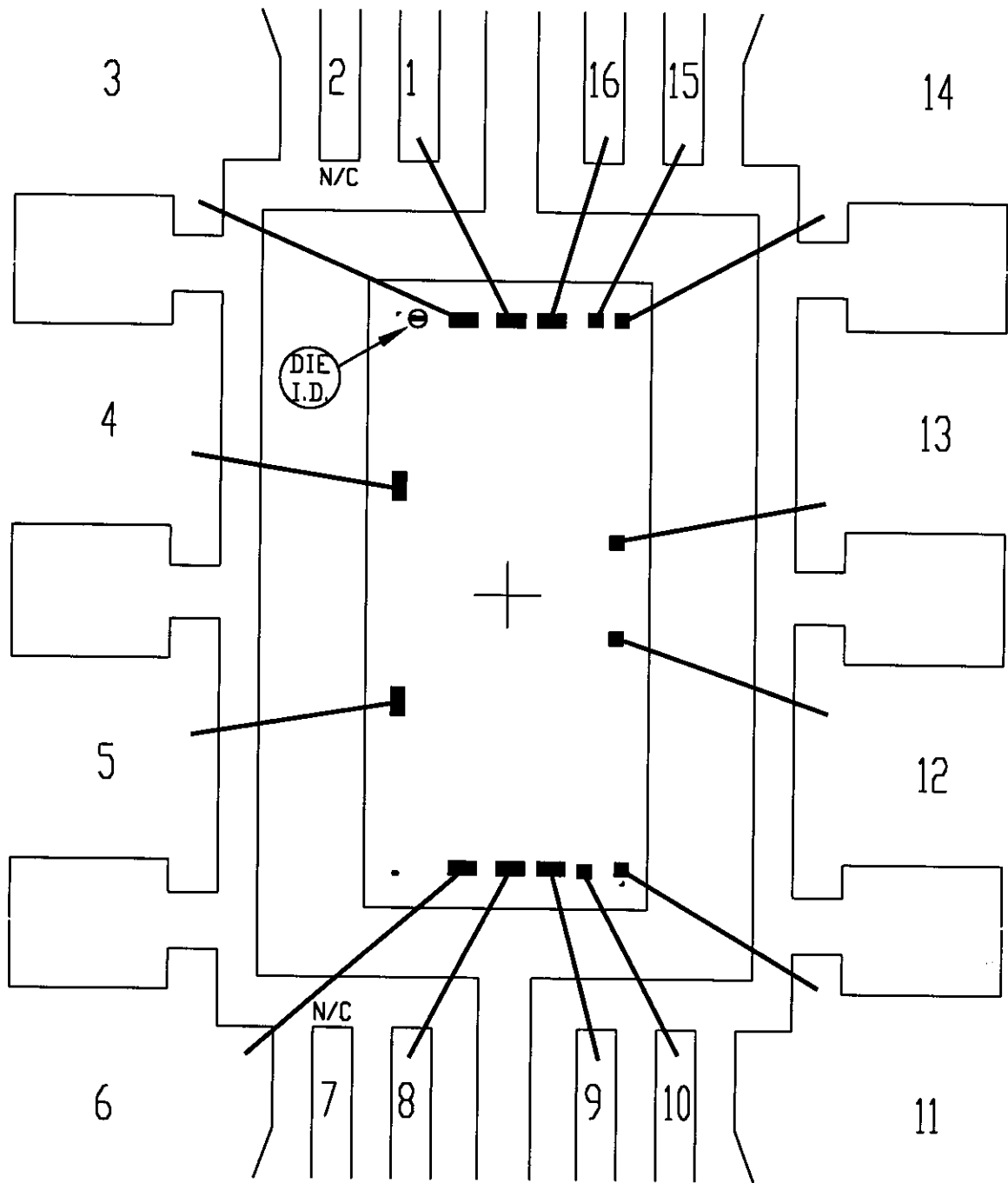
MAXIM

CAV./PAD SIZE:
102X220

PKG.
DESIGN

BUILDSHEET NUMBER:
05-1201-0084

REV.:
A



PKG.CODE: P16-4

CAV./PAD SIZE:
150 X 230

PKG.
DESIGN

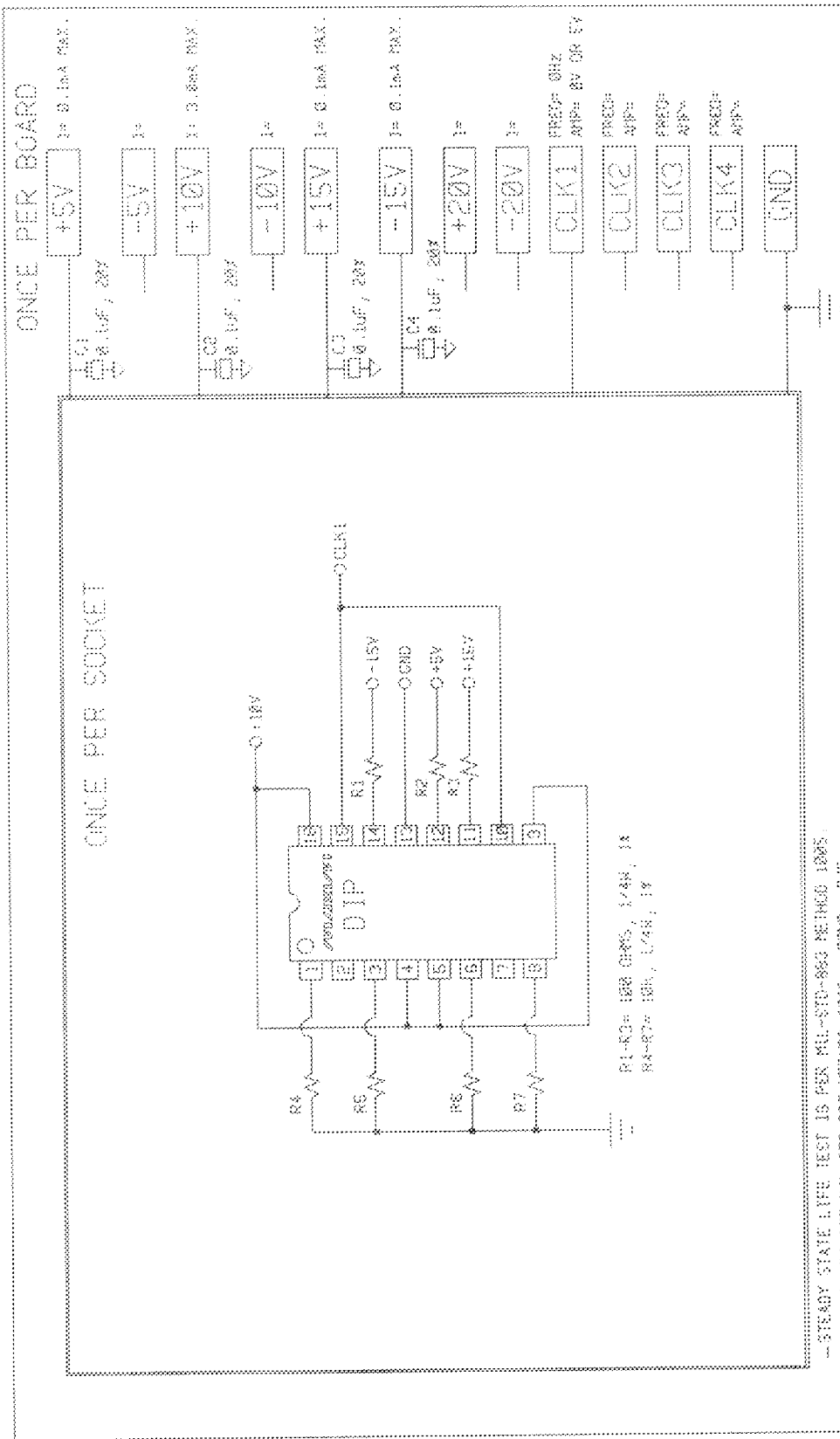
APPROVALS

DATE

MAXIM

BUILDSHEET NUMBER:
05-1201-0083

REV.:
A



— STEADY STATE LIFE TEST IS PER MIL-STD-883 METHOD 1005
 — BURN-IN IS PER MIL-STD-883 METHOD 1015, COND. B/C

| | |
|---|---|
| SPEC. NO. 06-1727 REV. E | MAX IM BURN-IN SCHEMATIC |
| NOTES: 1. TEMPERATURE: 100C OR EQUIVALENT 2. TIME: 150 HOURS MIN. OR EQUIVALENT 3. ALL COMPONENTS AND MATERIAL MUST STAND 150C CONTINUOUS 4. APPROVED FOR (X) COMMERCIAL (X) MR/880 | DATE: 4/26/85 SERVICE TYPE: DC: 06/4/88, 14E042/1/2/3/4/5/7/6/5 14E0550/1, 14E140/1/2/3/4/5/7/5 14E081/003/085 80-88 L/403/485 |